In the claims:

The following is a complete listing of all the claims in the application, with an indication of the status of each:

1. (Currently amended) A method for gluing microcomponents to a substrate in the production of microsystem components, comprising:

applying a reactive or nonreactive, pulverulent, hotmelt adhesive as a dispersion through a contoured screen with a result that said hotmelt adhesive is present only selected contact areas on a surface of at least one of a substrate and at least one microcomponent, said hotmelt adhesive not being present on other areas on said surface of said at least one of a substrate and at least one microcomponent; and

applying the at least one microcomponent to the substrate by melting the hotmelt adhesive on the contact areas when the hotmelt adhesive is between the at least one microcomponent and the substrate, and bonding the at least one microcomponent to the substrate during cooling of the hotmelt adhesive below its melting point.

2-3. (Canceled)

4. (Previously presented) The method of claim 1 wherein melting the hotmelt adhesive during the step of applying the at least microcomponent to the substrate is achieved using a laser as a heat source.

5-13. (Canceled)

14. (Previously presented) The method of claim 1 further comprising a step of preheating of the surface to which hotmelt adhesive is to be applied.

15. (Previously presented) The method of claim 1 further comprising a step of afterheating the at least one microcomponent after adhering to the substrate.

16. (Previously presented) The method of claim 15, wherein the afterheating takes place using a focused or global heat source.

17-18. (Canceled)

19. (Currently amended) A microsystem component having at least one microcomponent bonded to a substrate, wherein the adhesive bonding is performed by the method of:

applying a pulverulent hotmelt adhesive as a dispersion through a contoured screen to a surface of at least one of a substrate or at least one microcomponent,

melting of said hotmelt adhesive at selected bond sites on said surface by irradiating a powder layer on the selected bond sites using a focusable heat source;

removal of the powder layer not incipiently melted; and

adhering the at least one microcomponent to the substrate during cooling of the hotmelt adhesive.

20. (Previously presented) The microsystem component of claim 19, wherein the at least one microcomponent is smaller than 1000 μm.

21. (Canceled)